

HAT1043M

Silicon P Channel Power MOS FET Power Switching

REJ03G1151-0600 (Previous: ADE-208-754D)

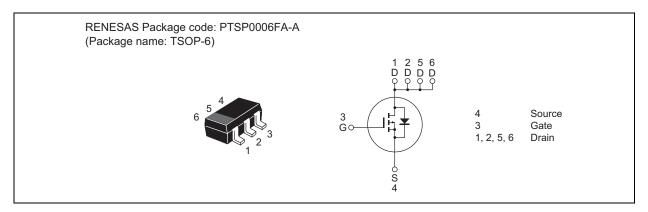
Rev.6.00

Sep 07, 2005

Features

- Low on-resistance
- Low drive current
- High density mounting
- 2.5 V gate drive device can be driven from 3 V source

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	-20	V
Gate to source voltage	V _{GSS}	±12	V
Drain current	I _D	-4.4	A
Drain peak current	I _{D (pulse)} Note 1	-17.6	A
Body-drain diode reverse drain current	I _{DR} Note 2	-4.4	A
Channel dissipation	Pch (pulse) Note 2	2.0	W
Channel dissipation	Pch (continuous) Note 3	1.05	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

- 2. When using the alumina ceramic board (50 \times 50 \times 0.7 mm), PW \leq 5 s, Ta = 25 $^{\circ}C$
- 3. When using the alumina ceramic board (50 \times 50 \times 0.7 mm), Ta = 25 $^{\circ}C$

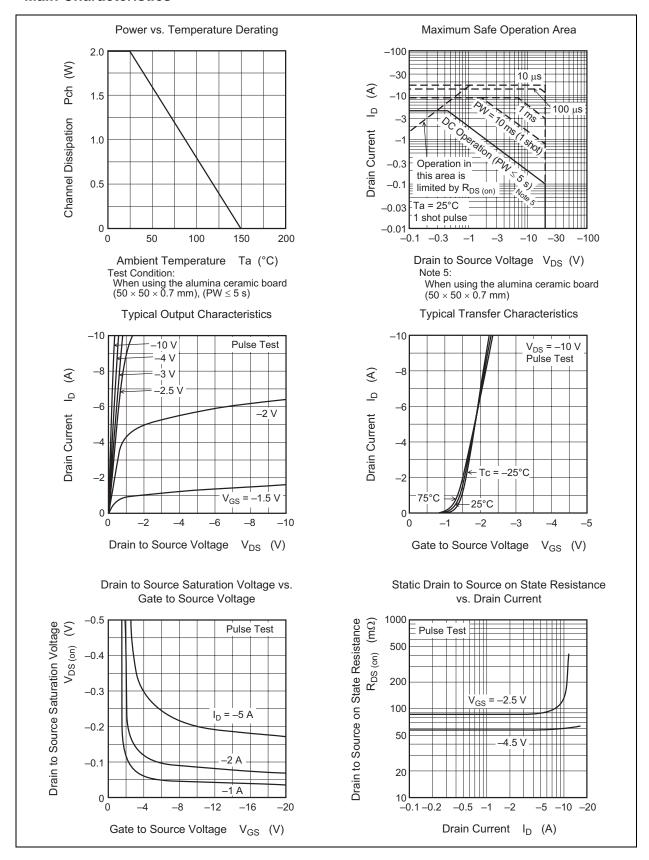
Electrical Characteristics

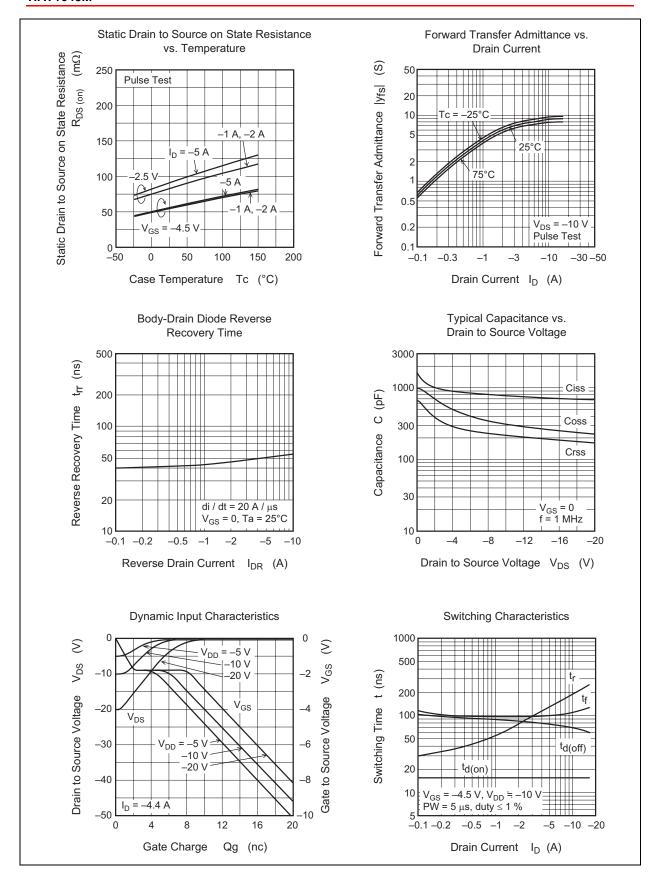
 $(Ta = 25^{\circ}C)$

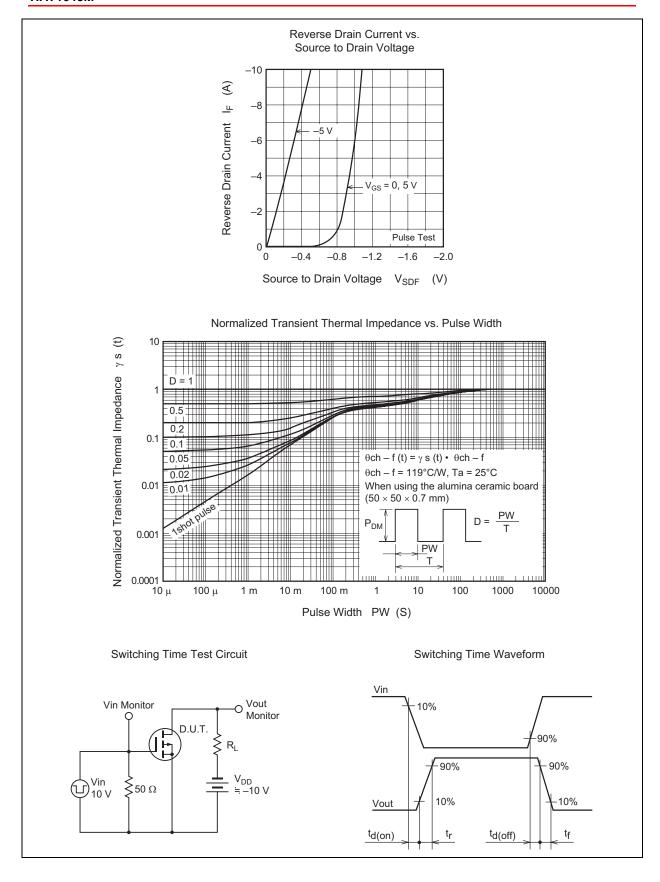
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	-20	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -20 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	-0.4	_	-1.4	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	R _{DS (on)}	_	55	65	mΩ	$I_D = -3 \text{ A}, V_{GS} = -4.5 \text{ V}^{\text{Note 4}}$
	R _{DS (on)}	_	85	110	mΩ	$I_D = -3 \text{ A}, V_{GS} = -2.5 \text{ V}^{\text{Note 4}}$
Forward transfer admittance	y _{fs}	4	7	_	S	$I_D = -3 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note 4}}$
Input capacitance	Ciss	_	750	_	pF	V _{DS} = -10 V
Output capacitance	Coss	_	310	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	220	_	pF	f = 1 MHz
Total gate charge	Qg	_	11	_	nC	V _{DD} = -10 V
Gate to source charge	Qgs	_	2	_	nC	$V_{GS} = -4.5 \text{ V}$
Gate to drain charge	Qgd	_	3.5	_	nC	$I_D = -4.4 \text{ A}$
Turn-on delay time	t _{d (on)}	_	15	_	ns	$V_{GS} = -4.5 \text{ V}, I_D = -3 \text{ A},$
Rise time	t _r	_	100	_	ns	$R_L = 3.3 \Omega$
Turn-off delay time	t _{d (off)}	_	85	_	ns	
Fall time	t _f	_	100	_	ns	
Body-drain diode forward voltage	V_{DF}	_	-0.95	-1.23	V	$I_F = -4.4 \text{ A}, V_{GS} = 0$
Body-drain diode reverse recovery time	t _{rr}	_	50	_	ns	$I_F = -4.4 \text{ A}, V_{GS} = 0$
						$di_F/dt = -20 A/\mu s$

Note: 4. Pulse test

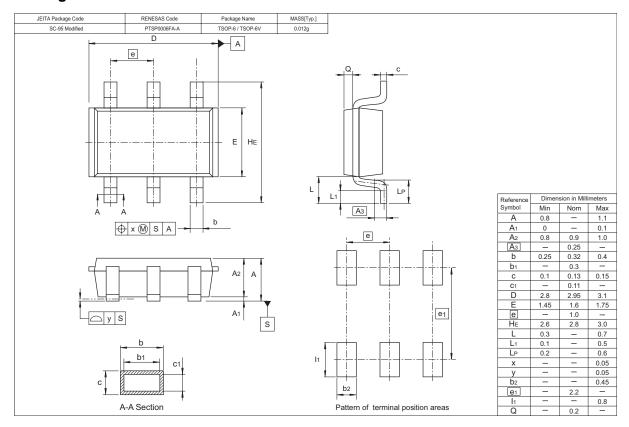
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT1043M-EL-E	3000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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